

Tektronix Component Solutions and MOSIS Ink ASIC Services Agreement Agreement Provides Complete ASIC Development Solution to Help Customers Cost Effectively Improve Time to First Packaged ASICs

BEAVERTON, Ore., August 7, 2012 - Tektronix Component Solutions, a custom microelectronics services provider, today announced an agreement with leading supply chain aggregator MOSIS to help customers develop complete, high-performance ASIC solutions while reducing the cost of early-stage ASIC development. Through the use of multi-project wafer runs for device prototyping and package development early in the design cycle, customers can cost-effectively improve the time to first packaged ASIC.

"The use of supply-chain aggregators like MOSIS is a proven development method for high-performance ASICs," said Tom Buzak, president of Tektronix Component Solutions. "We see our relationship with MOSIS as providing a complete, cost-effective ASIC solution for customers needing low-volume, high-performance devices."

By utilizing the MOSIS and Tektronix Component Solutions team, customers can reduce the cost of initial ASIC prototyping by employing multi-project wafer runs, rather than developing their own complete mask set prior to first silicon tape-out. Additionally, Tektronix Component Solutions can provide high-performance ASIC design on the front end and turnkey IC packaging services on the back end, rounding out a complete ASIC solution. By working with Tektronix Component Solutions early in the ASIC development process, customers can improve the time to first packaged device by designing the ASIC with package, external interconnect, and performance in mind.

For aerospace and defense contractors, medical OEMs, high-speed communications developers and others who require top performing ASICs, this relationship is especially relevant since both Tektronix Component Solutions and MOSIS are experienced working with a variety of high-performance semiconductor technologies. In particular, the organizations have proven expertise in developing high-speed ASICs on SiGe (silicon-germanium) processes. For aerospace and defense customers, the relationship offers a trusted supply chain since both Tektronix Component Solutions and MOSIS are accredited Trusted Suppliers, offering ASIC development and microelectronics assembly in a secure environment.

"As Tektronix' internal ASIC design and package development team, Tektronix Component Solutions brings impressive capabilities in developing high-performance microelectronic devices," said Wes Hansford, director of MOSIS. "We look forward to working with Tektronix Component Solutions to deliver custom ASIC solutions that meet the high-performance needs of our customers' next-generation systems."

About MOSIS

MOSIS is a low-cost prototyping and small-volume production service for VLSI circuit development. Since 1981, MOSIS has fabricated more than 70,000 circuit designs for commercial firms, government agencies, and research and educational institutions around the world.

About Tektronix Component Solutions

Tektronix Component Solutions is a proven microelectronics services provider offering a complete range of custom design, prototyping, manufacturing, and test services to equipment manufacturers. With more than 40 years of experience serving the measurement, military, medical, and communications markets, Tektronix Component Solutions works as an extension of customers' product teams to cost-effectively resolve the most demanding component challenges. Headquartered in Beaverton, Oregon, Tektronix Component Solutions can be found on the Web at component-solutions.tektronix.com.

<http://news.tektronix.com/news-releases?item=123038>